

Appl. No. 10/709,427  
Amdt. dated January 16, 2006  
Reply to Office action of November 08, 2005

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

5 1 (currently amended): A chip-packaging with bonding options having a plurality of package substrates, comprising:

a first package substrate having a high voltage or a low voltage;

a second package substrate having a high voltage or a low voltage, the voltage level of the first package substrate being the logical opposite of the voltage level of the second package substrate; and

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a chip mounted on first package substrate, the chip comprising a plurality of the bonding option pads, one bonding pad being connected to the first package substrate, another bonding pad being connected to the second package substrate; and

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a lead frame connected to one bonding pad,

wherein each bonding option pad of the chip is selectively connected to the first package substrate or the second package substrate.

2 (cancelled).

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3 (currently amended): The chip-packaging of the claim 2 claim 1 wherein the high voltage is the voltage of the power supply and the low voltage is the ground voltage.

4 (currently amended): The chip-packaging of the claim 1 further comprising a plurality

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of lead frames, wherein the each lead frame is connected to one pin of the chip-packaging.

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5 (original): The chip-packaging of the claim 4 wherein the pin is connected to a high voltage, a low voltage, or an input/output signal.

6 (original): The chip-packaging of the claim 1 wherein the first package substrate and the 5 second package substrate have different voltages.

7 (original): The chip-packaging of the claim 1 wherein the first package substrate extends outside the chip and the second package substrate surrounds the chip.

10 8 (currently amended): The chip-packaging of the claim 1 wherein the first package substrate and the second package substrate substantially approximate each of a plurality of the bonding option pads.

9-18 (cancelled).

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19 (new): The chip-packaging of the claim 4 wherein the pin is connected to an input/output signal.

20 20 (new): The chip-packaging of the claim 1 further comprising a plurality of lead frames, each bonding option pad of the chip having a corresponding lead frame, wherein each bonding option pad is selectively connected to the first package substrate, the second package substrate, or the corresponding lead frame.